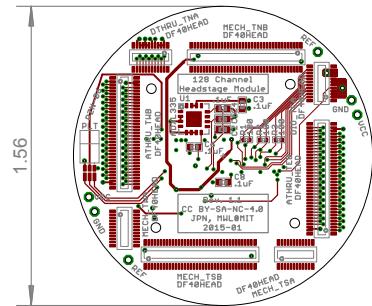


# RHD2164 Hirose Circular Headstage (Rev. 1.0) Board

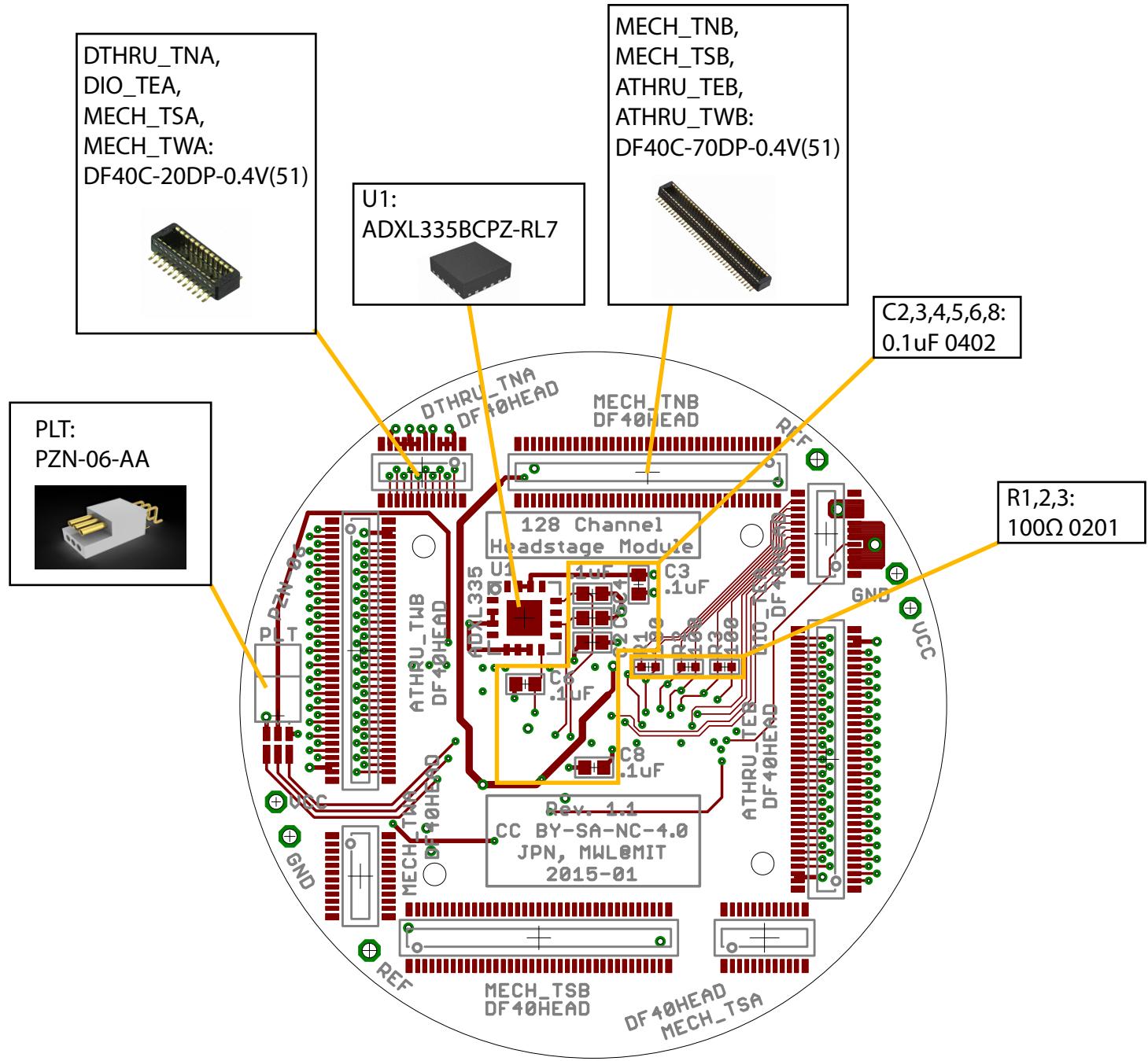
FR406 material, 0.036" thick, ENIG (immersion gold) plating (2 µinch)

No through-hole components; only SMDs



## Actual size

# Top Components (19 total)



## **Bottom Components (16 total)**

AIN\_BNB,  
ATHRU\_BWD,  
AIN\_BSB,  
ATHRU\_BEB:  
DF40C(2.0)-70DS-0.4V(51)



DTHRU\_BNA,  
MECH\_BWA,  
MECH\_BSA:  
DF40C(2.0)-20DS-0.4V(51)



C1,7:  
10nF 0201

**ATHRU\_BEB**  
**DF40REC**

R1,2,3:  
100kΩ 0201

U2:  
74HC4053

R4:  
00 0402

DF 7875 BB

1

**RHD2164 bare die**  
(7.3 mm x 4.2 mm,  
0.20 mm thick)  
86 total bondwires  
RHD2164 bare die

1 pad not bonded

2 pads not bonded

**RHD2164 bare die**  
(7.3 mm x 4.2 mm,  
0.20 mm thick)  
87 total bondwires  
**RHD2164 bare die**

1 pad not bonded

1 pad not bonded

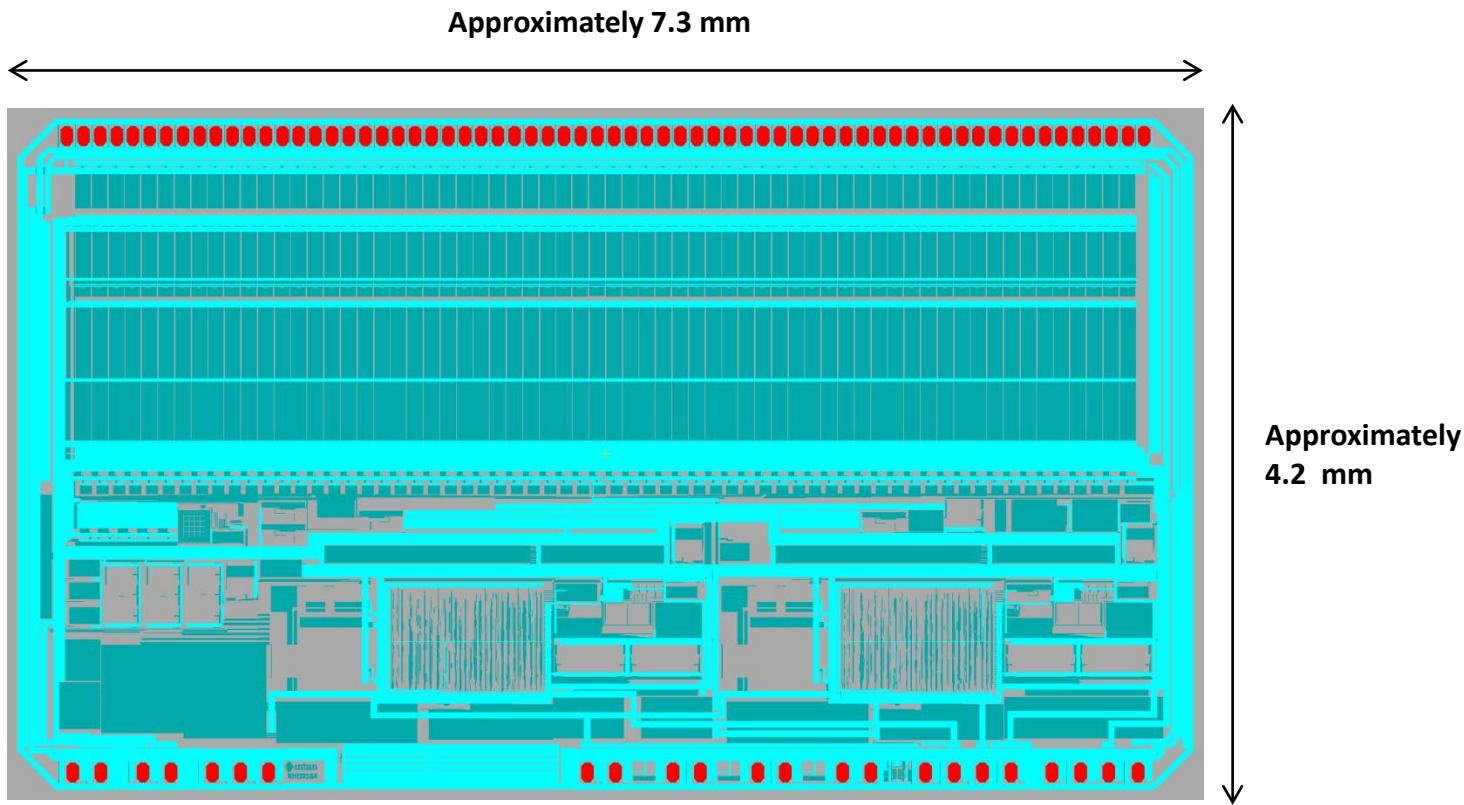
# Intan Technologies RHD2164 Bare Die

Gray = approximate outline of die (may vary from die to die due to variations in sawing)

**Yellow Cross** = center of design (may not coincide precisely with center of die due to variations in sawing)

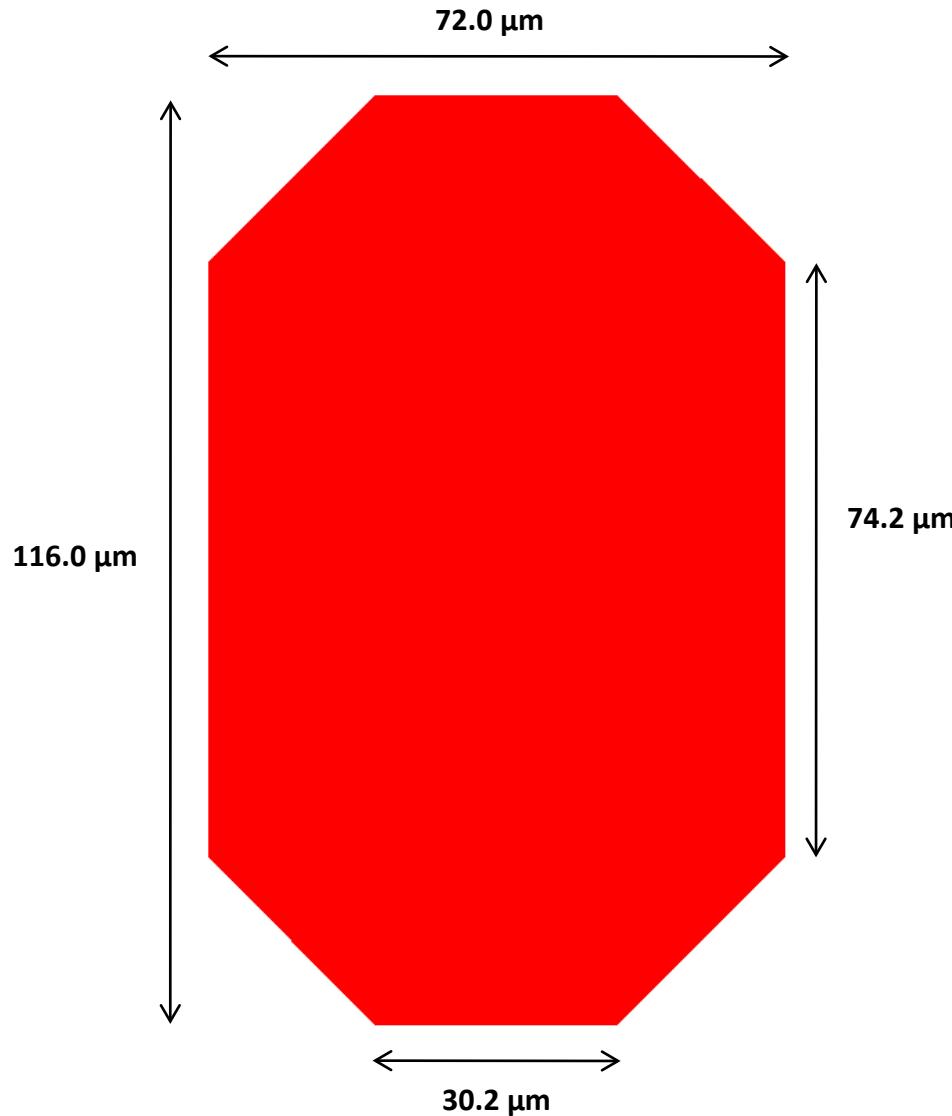
**Blue, Green** = top metal layers (highly visible)

**Red** = glass openings for bond pads



# Bond Pad Dimensions

Bond pad metal: AlCu (99.5% aluminum, 0.5% copper)



Minimum bond pad pitch (center to center) on RHD2164: 101.6 µm (4.000 mil)